

Customer Code : _____

DATASHEET

DAPU P/N: **DP7J10000001**

Plot			The Label
Drew	Audited	Approved	Stamp, please! Thanks!
Date: 2018.12.11			

Guangdong Dapu Telecom Technology Co.,Ltd

Bldg16,.N.Ind.Zone,SSL Industry Park, Dongguan City, Guangdong Province, China

TEL: 0086-0769-88010888 FAX: 0086-0769-81800098

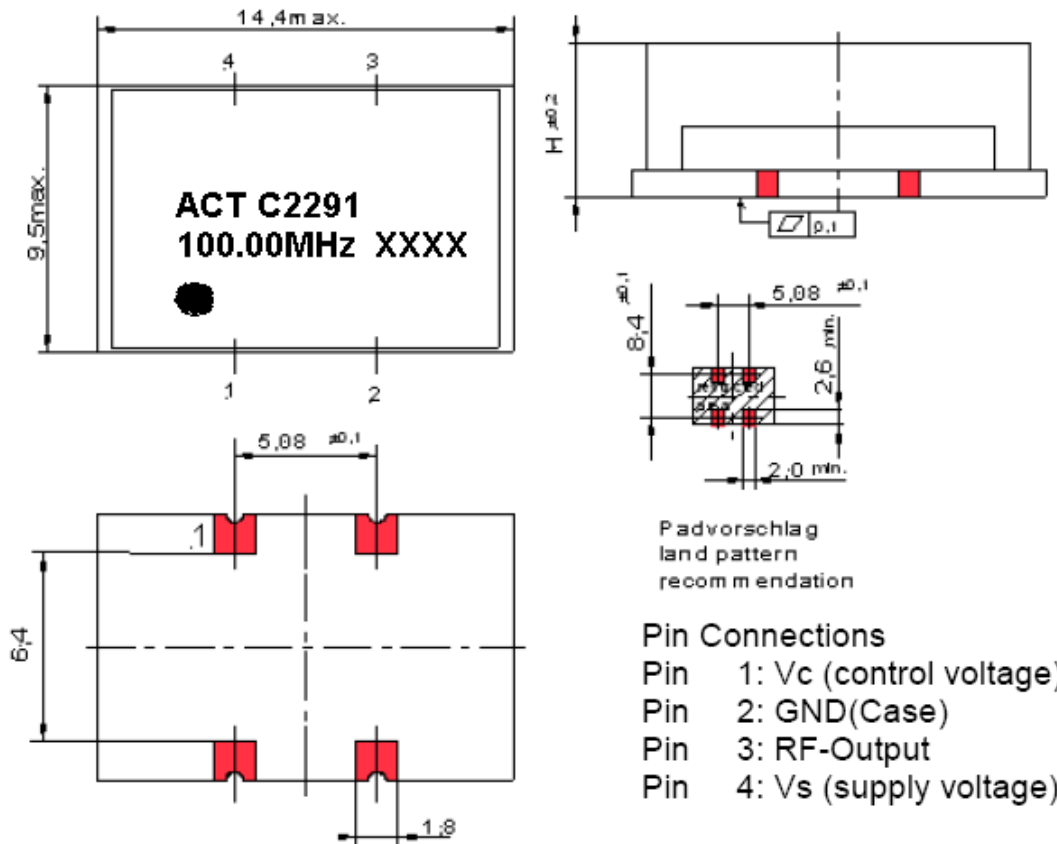


1、Electrical Parameters

MODEL: DP7J1000001							
No	Parameters	SYM.	Electrical Spec.				Notes
			Min.	Typ.	Max.	Units	
1	Nominal Frequency	FL	100.00			MHz	
2	Output Waveform		LVCMOS				
4	Supply Voltage		3.13	3.3	3.47	V	
5	Frequency Tolerance		-20		+20	$\times 10^{-6}$	incl. df vs initial, temp -40...85°C, dVs, dLoad, aging
6	Absolute pulling range (APR)	df/f0	-20		+20	$\times 10^{-6}$	ext.turing voltage @0 to 3.3V
7	Linearity				10	%	
8	slope		positive				
9	Frequency control input impedance				1000	kOhm	
10	Current Consumption steady state				24	mA	@Vsnom &25°C
11	Rise Time	Tr			3	ns	@20% to 80% Vout
12	Full Time	Tf			3	ns	@80%~20% Vout
13	Duty Cycle	DC	45	50	55	%	@1.65V
14	V Low				0.3	V	
15	V High		2.97			V	
16	Spurious				-100	dBc	
17	Phase Noise				-70	dBc/Hz	@10Hz
					-100		@100Hz
					-130		@1000Hz
					-150		@10kHz
					-160		@100kHz
					-162		@1000kHz
18	Storage Temperature	T-stg	-45		90	°C	
19	Jitter		<1.000 psec RMS				@12kHz to 80MHz
20	Rapid temperature changes		MIL-883-1010 Cond B 1000 cycles -55/125°C				
21	Vibration		MIL-STD-883 Meth 2007 Cond A 20G 20-2000Hz 4x in each 3axis 4 min				
22	shock		MIL-STD-202 Meth 213 Cond.C 100G 6ms 6 shocks in each dirwction				
23	Solderability		J_STD_002B Cond A lesded/ Cond. B SMD 245°C (diving Time 5+0,5sec.) Dip+Look with 8h damp pre-treatment:solder wetting>95%				
24	Solvent resistance		MIL-STD-883 Meth 2015 Solv.1,3,4				
25	ESD		HBM JESD22-A Class 1 10* 1000V				
26	Moisture Sensit		Level 1 JESD22-A113-B				



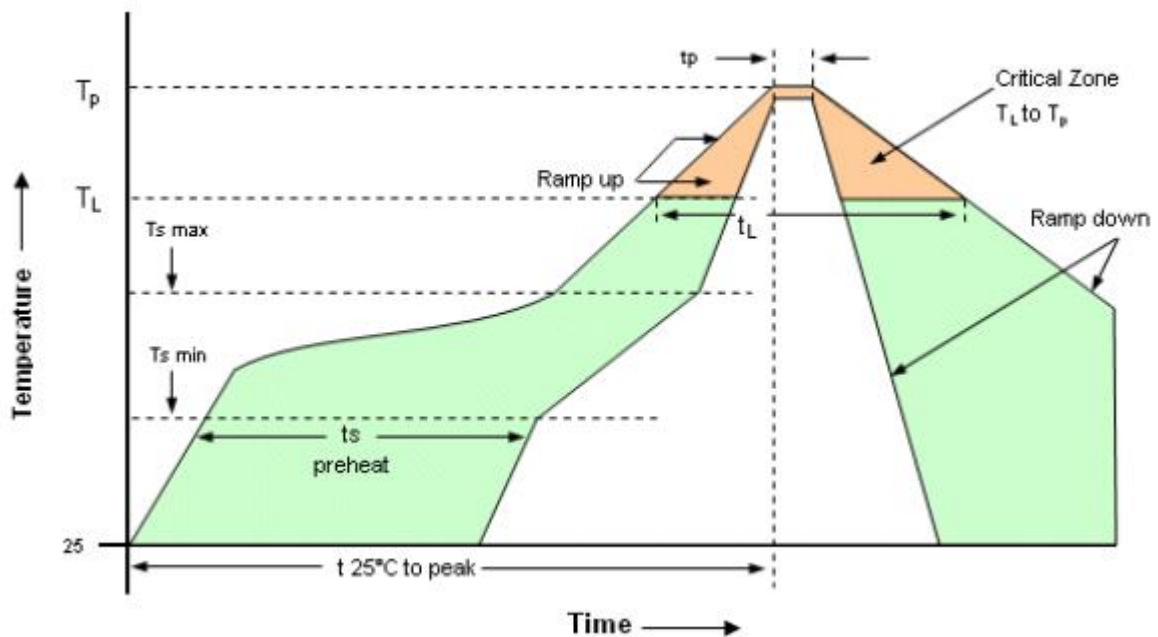
2、Mechanical Structure(mm)



unit:mm

Note1: The first two xx representative : year
After two xx representative: week

3、Reflow profile





Profile Feature	Pb-Free Assembly/Sn-Pb Assembly
Average ramp-up rate (TL to Tp)	3°C/second max.
Preheat -Temperature Min (T _{min})	150°C
-Temperature Min (T _{max})	200°C
-Time (min to max) (ts)	60-180 seconds
T _{max} to TL - Ramp-up Rate	3°C/second max.
Time maintained above - Temperature (TL)	217°C
- Time (TL)	60-150 seconds
Peak Temperature (Tp)	max 260°C
Time within 5°C of actual Peak Temperature (tp)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.
Note: All temperatures refer to topside of the package, measured on the package body surface.	
Additional Information	
This SMD oscillator has been designed for pick and place reflow soldering. SMD oscillators must be on the top side of the PCB during the reflow process.	

4、 Standard shipping method

